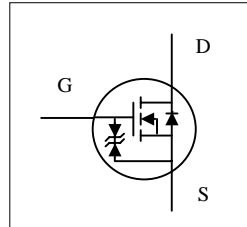
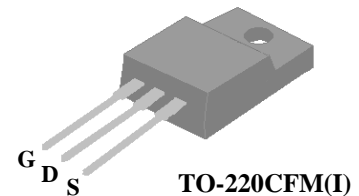




- ▼ 100% Avalanche Test
- ▼ ESD Improved Capability
- ▼ Simple Drive Requirement
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	700V
$R_{DS(ON)}$	7 Ω
I_D	1.6A



Description

AP02N70 from APEC provide the designer with the best combination of fast switching , low on-resistance and cost-effectiveness .

The TO-220CFM isolation package is widely preferred for commercial-industrial through hole applications.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	700	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	1.6	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	1	A
I_{DM}	Pulsed Drain Current ¹	6.4	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	27.8	W
E_{AS}	Single Pulse Avalanche Energy ²	13	mJ
I_{AR}	Avalanche Current	1.6	A
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	4.5	$^\circ C/W$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	65	$^\circ C/W$



AP02N70EI-HF

Electrical Characteristics @T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	700	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} =10V, I _D =0.8A	-	-	7	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	-	4	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =0.8A	-	0.65	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =600V, V _{GS} =0V	-	-	10	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±10	uA
Q _g	Total Gate Charge	I _D =0.8A	-	17	30	nC
Q _{gs}	Gate-Source Charge	V _{DS} =560V	-	1.5	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	11	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =350V	-	10	-	ns
t _r	Rise Time	I _D =0.8A	-	8	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =4.7 Ω	-	21	-	ns
t _f	Fall Time	V _{GS} =10V	-	15	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	170	300	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	30	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ³	I _S =1.6A, V _{GS} =0V	-	-	1.5	V
t _{rr}	Reverse Recovery Time	I _S =1.6A, V _{GS} =0V,	-	340	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	-	2550	-	nC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Starting T_j=25°C, V_{DD}=50V, L=10mH, R_G=25Ω, I_{AS}=1.6A.
3. Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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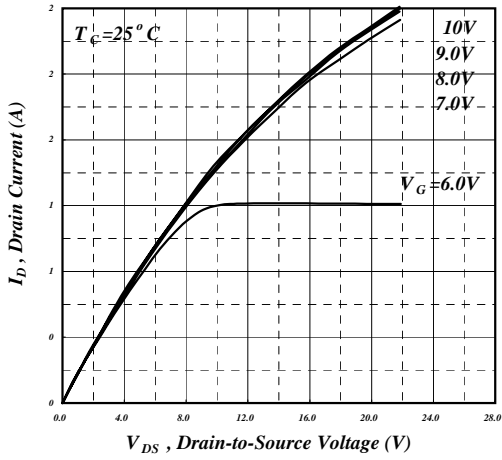


Fig 1. Typical Output Characteristics

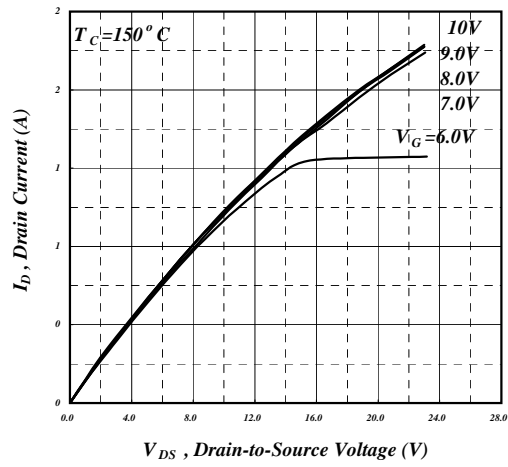


Fig 2. Typical Output Characteristics

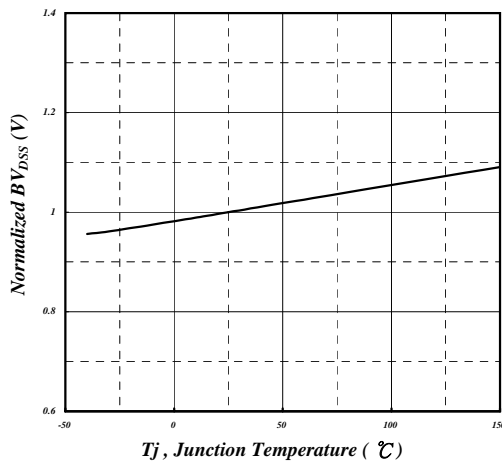


Fig 3. On-Resistance v.s. Gate Voltage

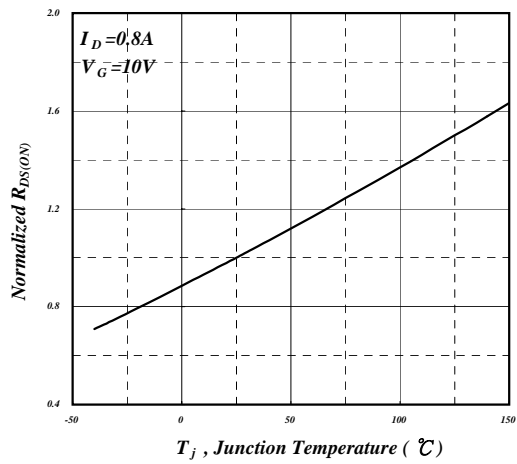


Fig 4. Normalized On-Resistance v.s. Junction Temperature

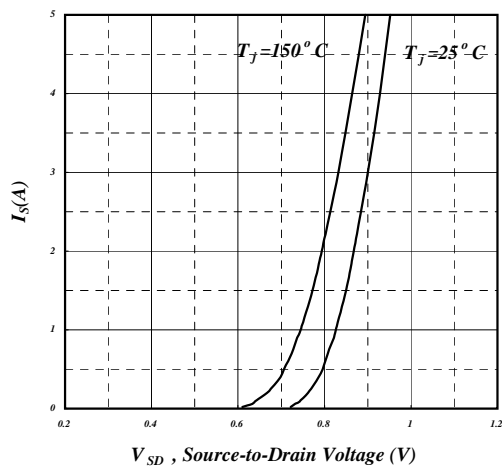


Fig 5. Forward Characteristic of Reverse Diode

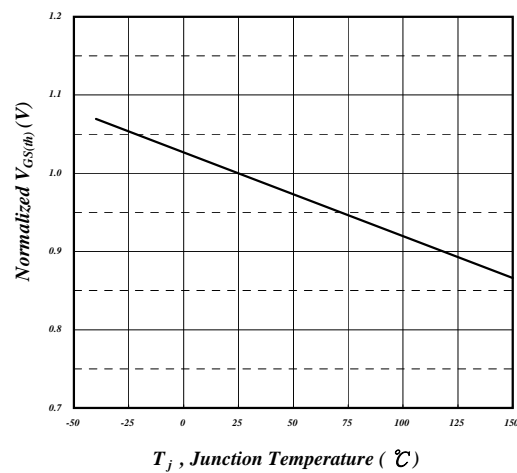


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

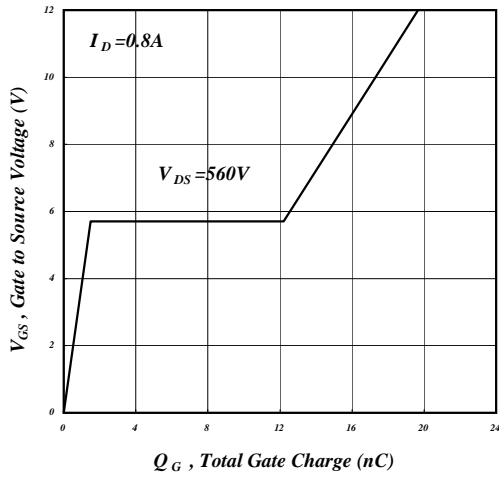


Fig 7. Gate Charge Characteristics

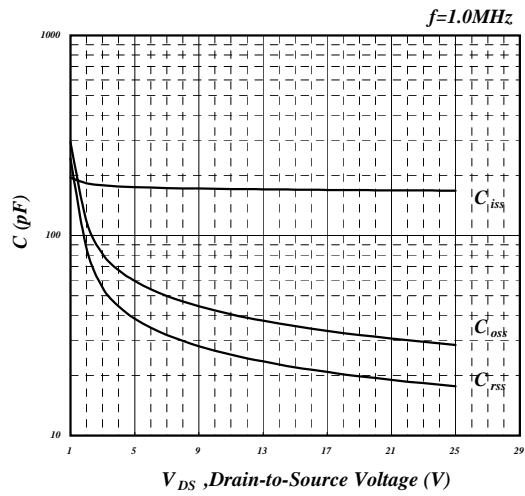


Fig 8. Typical Capacitance Characteristics

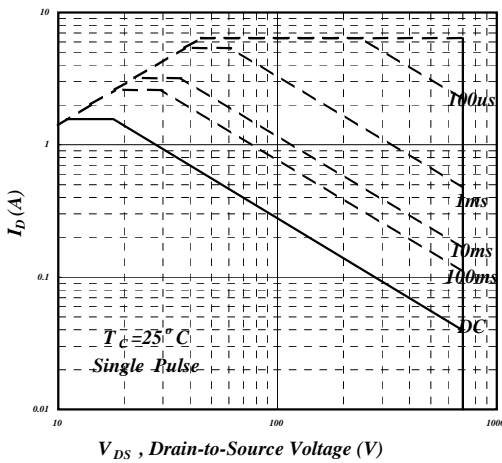


Fig 9. Maximum Safe Operating Area

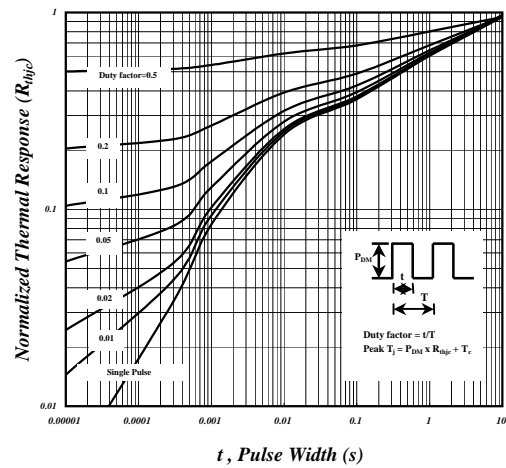


Fig 10. Effective Transient Thermal Impedance

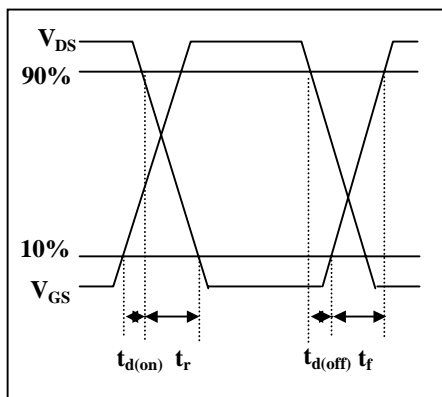


Fig 11. Switching Time Waveform

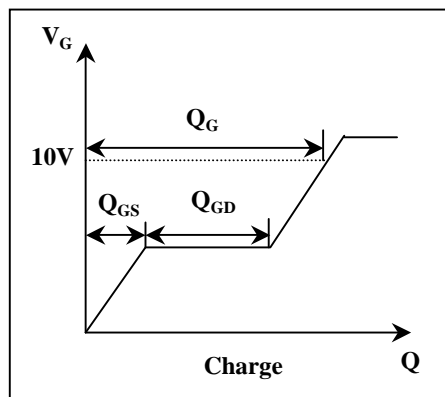


Fig 12. Gate Charge Waveform